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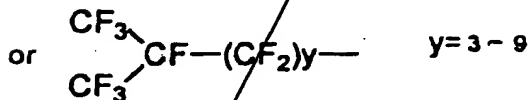
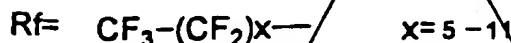
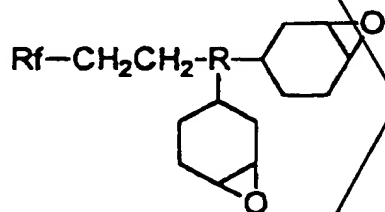
WHAT IS CLAIMED IS:

1. A fluorine-containing epoxy resin composition, comprising:

a fluorine-containing epoxy resin having in one molecule at least one perfluoroalkyl group having 6 to 12 carbon atoms and at least two alicyclic epoxy groups, and

a cationic polymerization catalyst.

2. The fluorine-containing epoxy resin composition according to claim 1, wherein the fluorine-containing epoxy resin is an epoxy compound represented by the following Formula (A-1):

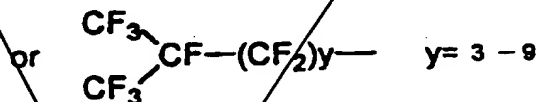
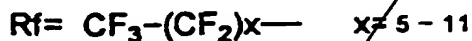
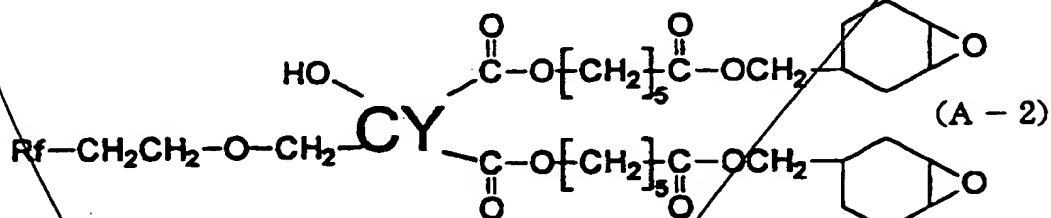


(A - 1)

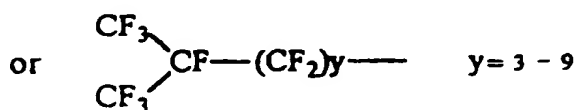
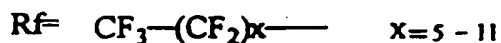
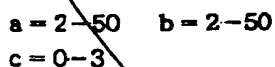
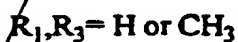
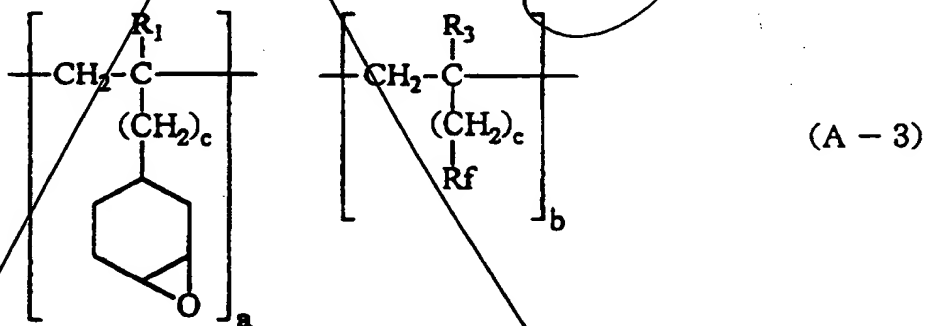
wherein R is an aliphatic residue for linking monomers each having an alicyclic epoxy group.

3. The fluorine-containing epoxy resin composition according to claim 1, wherein the

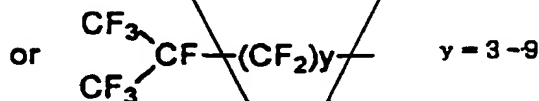
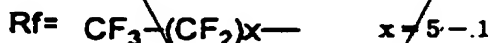
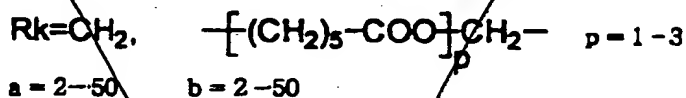
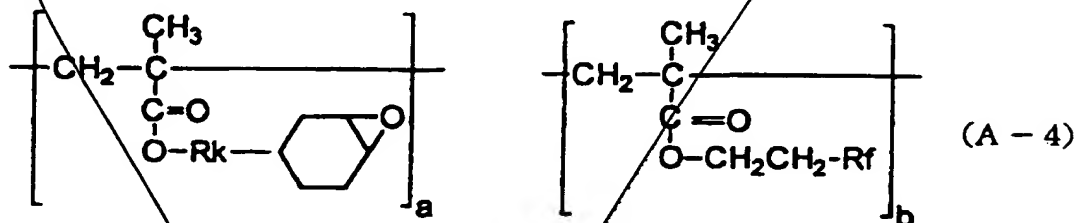
fluorine-containing epoxy resin is an epoxy compound represented by the following Formula (A-2):



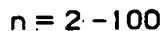
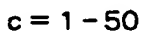
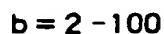
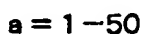
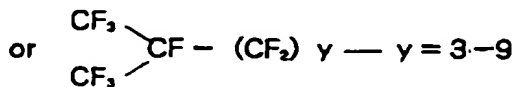
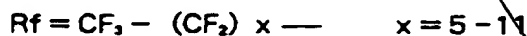
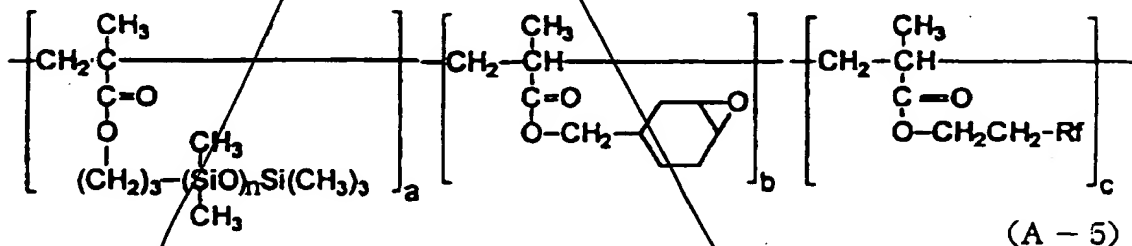
4. The fluorine-containing epoxy resin composition according to claim 1, wherein the fluorine-containing epoxy resin is an epoxy polymer represented by the following Formula (A-3):



5. The fluorine-containing epoxy resin composition according to claim 1, wherein the fluorine-containing epoxy resin is an epoxy polymer represented by the following Formula (A-4):



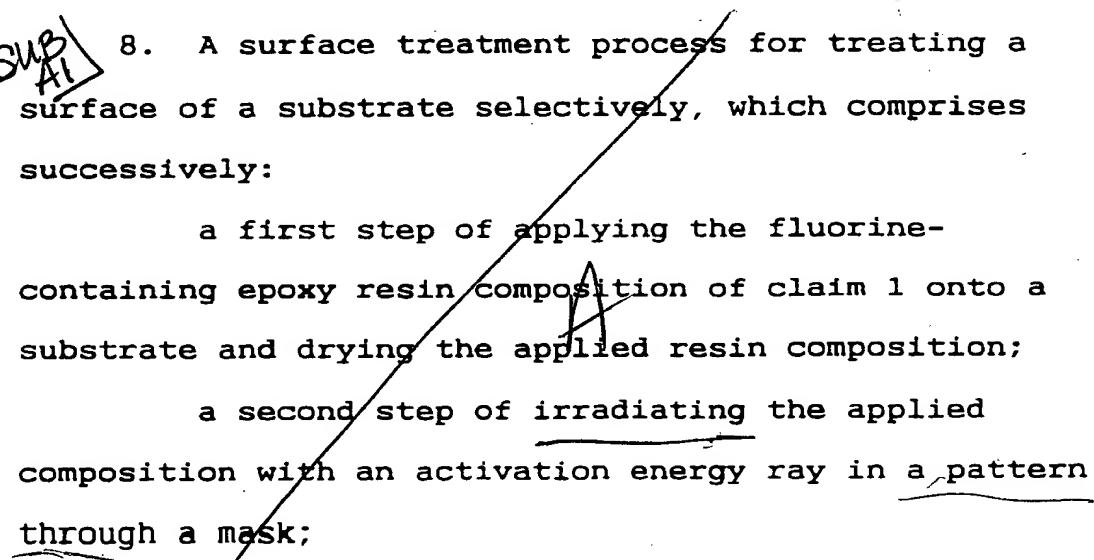
6. The fluorine-containing epoxy resin composition according to claim 1, wherein the fluorine-containing epoxy resin is an epoxy polymer represented by the following Formula (A-5):



$$\text{CH}_2=\text{CH}-\text{CH}_2-\text{O}-\left[\text{C}_6\text{H}_4-\text{C}(\text{CF}_3)_2-\text{C}_6\text{H}_4-\text{O}-\text{CH}_2-\underset{\text{OH}}{\text{CH}}-\text{CH}_2-\text{O}-\text{C}_6\text{H}_4-\text{C}(\text{CF}_3)_2 \right]_p-\text{C}_6\text{H}_4-\text{OCH}_2\text{CH}=\text{CH}_2$$

$p=0-2$

(C-1)



a first step of applying the fluorine-containing epoxy resin composition of claim 1 onto a substrate and drying the applied resin composition;

a second step of irradiating the applied composition with an activation energy ray in a pattern through a mask;

a third step of dissolving and removing a part of the applied composition not irradiated with the activation energy ray, by use of a liquid capable of dissolving the uncured composition; and if desired

5 a fourth step of post-curing the remaining composition.

9. A surface treatment process for treating a surface of a substrate selectively, which comprises successively:

10 a first step of applying the fluorine-containing epoxy resin composition of claim 1 onto a substrate and drying the applied resin composition;

15 a second step of heating or irradiating with an activation energy ray the applied composition to effect polymerization and curing over a whole area thereof;

20 a third step of selectively irradiating the cured composition with a breaking activation energy ray to partly remove the cured composition; and if desired

a fourth step of post-curing the remaining composition.

10. An ink jet recording head having a discharge opening surface with a discharge opening for discharging a recording liquid therethrough, wherein at least a discharge opening formed portion of the

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25
gms.

